

# Satellite EOS(Electronic optical system) CCD(charge coupled device) detector control driver module design

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**Abstract:** The CCD (Charge coupled device) detector that is used to convert the light into electronic data is very important component in satellite camera. A Linear CCD Spectral detector shall be used in the MSC (Multi-Spectral Camera, to obtain data for high-resolution images) Payload. In this paper, the design concept of the CCD detector control module in the MSC CEU (Camera electronic unit) system which will be a payload on KOMPSAT is described in terms of H/W (clock speed and accuracy).

The EOS is slave to the PMU and fully controlled by the PMU. The EOS receives the required power supplies from the Power Supply Module (PSM) of the PMU. The EOS is continuously thermally controlled by the THTM module of the PMU.

## 1. Introduction

The detector consists of 3 parallel arrays in the MSC. Each array consists of 5200 active elements with 32 TDI stages. The number of TDI stages is externally selectable in predefined stages. This control module shall be included in the FPE (Focal Plane Electronics) of CEU. The FPE board receives operating voltages from an external source. The FPE board supplies voltages (required power) as well as clocks (timing) to the CCD detector. Precise timing is supplied to the detector to ensure optimal operation in each operational mode.

## 2. EOS system

The EOS consists of two Electro-optical channels: Panchromatic (PAN) and Multi-Spectral (MS) sharing the same mirror telescope. Both channels can perform imaging at synchronous rate (nominal ground scan speed of ~6800 m/s). The EOS shall cover a swath width of 15km from an altitude of 685 km. The PAN channel has 15,000 active pixels of 1m ground resolution. Fig.1 is EOS block diagram.

The incoming light is converted to electronic analog signals by the detectors in the DFPA. The analog signals are amplified, biased and converted into digital signals (pixel data stream) in the FPE.

The digital data is transmitted to the Payload Management Unit (PMU) for pre-processing to correct for non-uniformity, to partially reorder the pixel stream (in the MS channel only) and to add header data for identification and synchronization.

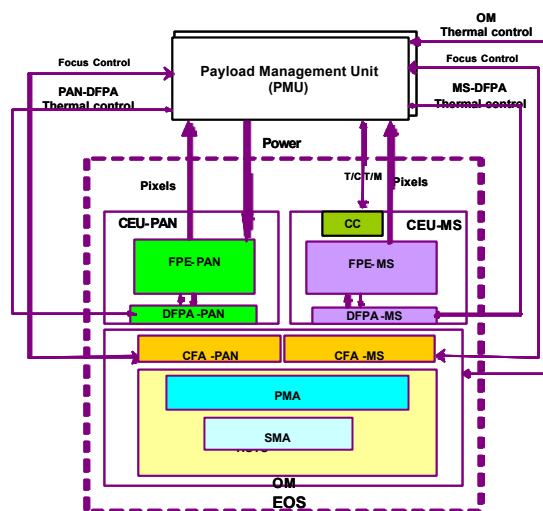


Fig.1 EOS Block diagram.

## 3. FPE system

The FPE assembly shall support the detector with the required power and timing. It shall process the analog signals, which come out of the detector and convert them to digital form. The FPE assembly shall consist of a single detector, up to twelve video channels, clock drivers, voltage regulators and control lines.

The fig.2 is the detector block diagram. The Detector is a Linear CCD Spectral detector. The Spectral separation is achieved by a customer supplied Spectral Input Window attached on the case. The detector consists of 3 parallel arrays. Each array consists of 5200 active elements with 32 TDI stages. The number of TDI stages is externally selectable in predefined stages. Electro-optical testing of the detector shall be carried out with a Clear input Window, for both options (PAN & MS).



The diagram illustrates a dual-channel system architecture. Two identical processing modules are connected to a central bus. Each module contains an FPGA, Video Processors, Clock drivers, and Power Management blocks. The modules are connected to PMUs via Hot Links and to a central bus via Interfaces. The central bus is connected to a CC through an Internal Bus and to POWER and Ser. Comm. lines.

**Fig.3 CEU PAN block diagram**

The development of the FPE will be based on advanced design methods and tools, and will make use of novel advanced components and technology (authorized for spaceborne use), in order to reduce size, power consumption and weight and enhance performances. The FPE shall be designed to operate in IMAGING mode with up to 20% duty cycle per orbit; i.e. of up to 20 minutes during a 100 minutes orbit period.

In this paper, the high speed clock driver circuit (PL, PLS, PR) is described. The fig.4 is pixel timing diagram for PL, PLS, PR. It has 11 Mhz pixel rate(8,000 lines/sec).

$$\text{Tr/Tf}(\ddot{\text{O}}\text{LSij}) = \text{Tr/Tf}(\ddot{\text{O}}\text{Rij}) = 0.05*(1/\text{Fpixel}) \text{ to } 0.1*(1/\text{Fpixel})$$

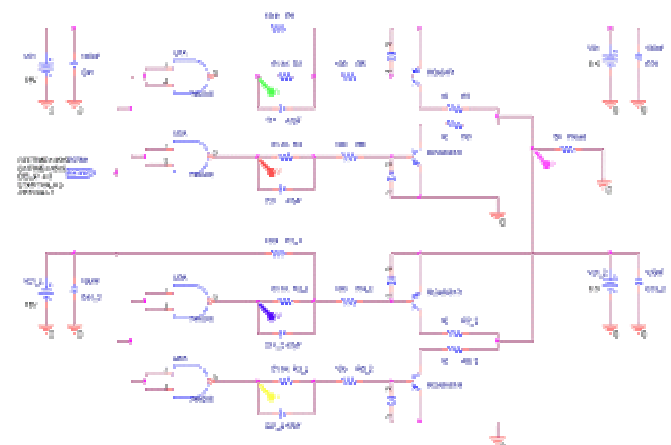
The timing diagram illustrates the relationship between several signals over time. The signals shown are:

- $\Phi L1$  and/or  $\Phi$
- $\Phi L2$  and/or  $\Phi$
- $\Phi LS_{ij}$
- $\Phi Ri_j$
- CCD sig-

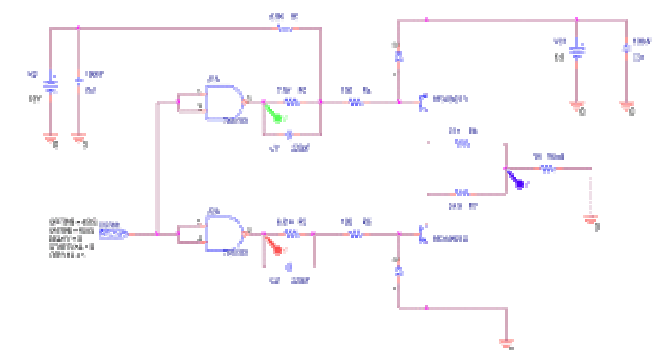
Key timing parameters and transitions are indicated:

- Transitions:** Vertical dashed lines mark specific signal transitions.
- Horizontal Arrows:** Indicate signal durations.
  - For  $\Phi L1$  and/or  $\Phi$ : # 25 ns (# 10 ns), 20 ns, 15 ns, 20 ns, 15 ns.
  - For  $\Phi LS_{ij}$ : # 40 ns (# 20 ns), ns, # 40 ns (# 20 ns).
  - For  $\Phi Ri_j$ : 5 ns, 10 ns, 5 ns, # 70 ns (# 35 ns).
- Levels:**
  - single level:** Indicated for the CCD sig- signal.
  - reference level:** Indicated for the  $\Phi Ri_j$  signal.
  - reset feedthrough:** Indicated for the CCD sig- signal.

#### Fig.4 Pixel Timing Diagram



**Fig.5 PL clock driver circuit**



**Fig.6 PLS and PR clock driver circuit**

The sharpness for clock signal in the fig.7 and the fig.8 is decided that resistance and capacitance value in the fig.5 and the fig.6 same as the fig.3 timing diagram.

The fig.7 is the result of the simulation for resistance and capacitance. ( $R=7.5K$ ,  $C=220pF$ )

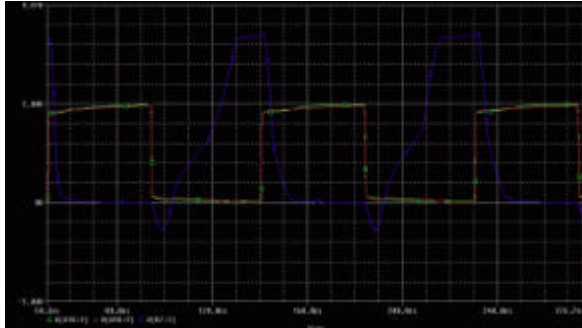


Fig.7 simulation result ( $R=7.5K$ ,  $C=220pF$ )

The fig.8 is the result of the simulation for resistance and capacitance. ( $R=7.5K$ ,  $C=100pF$ )

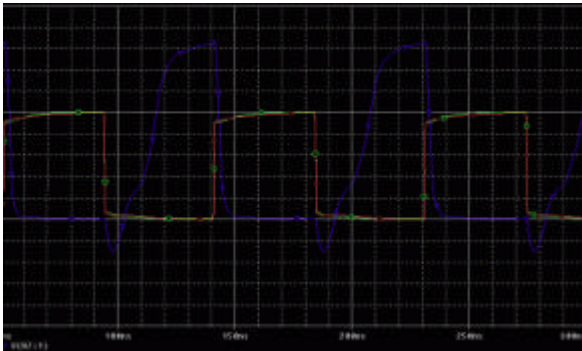


Fig.8 simulation result ( $R=7.5K$ ,  $C=100pF$ )

As the results of fig.7 and fig.8, the sharpness of timing diagram is changed by capacitance value.

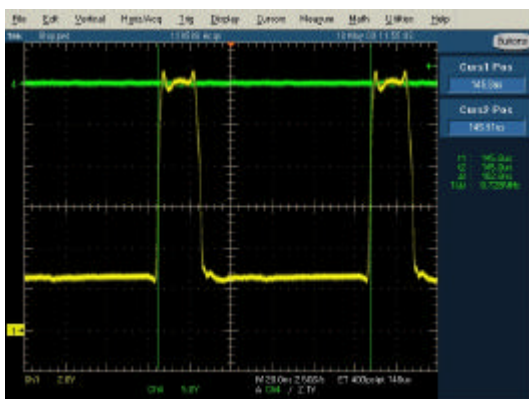


Fig.9 FPE PAN R34 clock signal.

From the fig.9 to the fig.11, these signals are the real signals captured by scope in this paper. These signals control and receive the video data from the CCD detector.

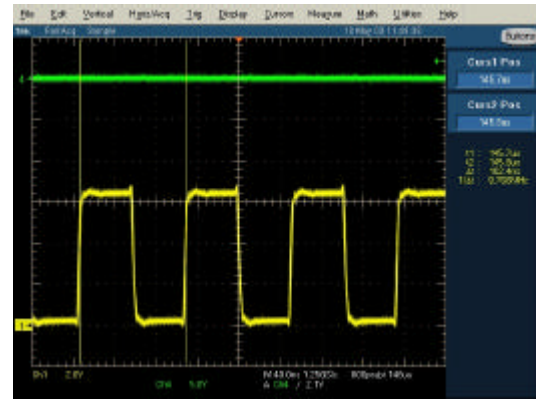


Fig.10 FPE PAN LS34 clock signal

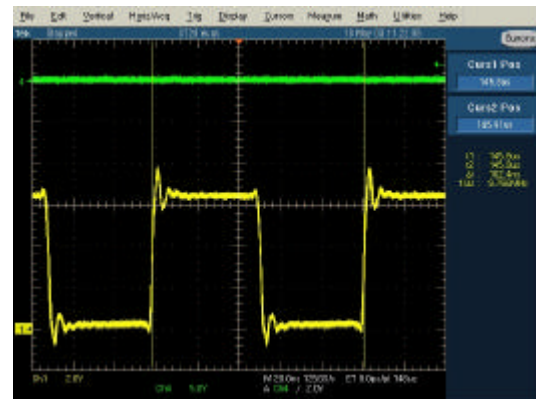


Fig.11 FPE PAN L4 clock signal

## 5. Conclusions

In this paper, the design concept of a CCD detector control module which is described in terms of H/W (clock speed and accuracy supplied to detector). The exact and sharp control clocks will get the accurate and efficient analog video signal from detector. Also the MSC is intended to be a small lightweight camera. The development of the FPE will be based on advanced design methods and tools, and will make use of novel advanced components and technology (authorized for spaceborne use), in order to reduce size, power consumption and weight and enhance performance

## References

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